

Press

27 March 2017

SMT Hybrid Packaging 2017
International Exhibition and Conference
for System Integration in Micro Electronics
Nuremberg, Germany, 16 – 18 May 2017

Bernhard Ruess
Tel. +49 711 61946-76
bernhard.ruess@mesago.com
smthybridpackaging.com

SMT Hybrid Packaging 2017: Advanced training platform with early-bird benefits

The countdown is on: Conference and tutorials of SMT Hybrid Packaging 2017 attract with early-bird prices until 3 April 2017. Interested participants can save a seat at the desired paper and increase their professional know-how. The tutorials will give answers to relevant questions in the field of electronic manufacturing from design to process technology up to quality assurance.

Short-tutorials with the latest know-how

The short-tutorials, held for the first time on SMT Hybrid Packaging 2017, enjoy great popularity. Eight different short-tutorials with a duration of 90 minutes are offered for an early-bird-price.

For example, Dr. Lee Hitchens from Nexus Ltd. will present a short tutorial on a new hybrid coating process that provides superior physical and electrical properties compared to traditional conformal coatings and Parylene but at a fraction of the cost:

“Combining several technologies in a simple turnkey system this easy to operate novel technique provides top-class barrier protection against water, moisture and chemicals in high volume electronics like LEDs, tablets, mobile phones and automotive assemblies while requiring no masking, is completely hydrophobic, is 100 percent optically transparent, temperature stable up to 350°C and completely UV stable.”

The top-class program is completed by the conference and the tutorials with a duration of three hours for an early-bird price. Internationally known tutorial speaker Dr. Jennie S. Hwang, H-Technologies Group Inc., gives a holistic overview of product reliability and of critical “players” of the SMT assembly integrity and solder joint reliability:

“Under today’s market and manufacturing environment, the effort to maximize production yield, reduce cost and assure product reliability is

Mesago Messe Frankfurt GmbH
Rotebuehlstr. 83 – 85
70178 Stuttgart, Germany
mesago.com

Board of Management:
Petra Haarbuerger
Martin Roschkowski

Register Court: Local Court Stuttgart,
HRB 13344

becoming increasingly important to a company's competitiveness. [...] The tutorial emphasizes on practical working knowledge including the important roles of materials, processes and testing/service conditions, as well as the crucial principles behind the product reliability", says Dr. Hwang and encourages participants to interact and bring their own selected systems for deliberation.

The complete conference program and further information about the tutorials can be found online at smthybridpackaging.com/conference.

About Mesago

Mesago, founded in 1982 and located in Stuttgart, specializes in exhibitions and conferences on various topics of technology. The company belongs to the Messe Frankfurt Group. Mesago operates internationally and is not tied to a specific venue. With 130 members of staff Mesago organizes events for the benefit of more than 3,300 exhibitors and over 110,000 trade visitors, conference delegates and speakers from all over the world. Numerous trade associations, publishing houses, scientific institutes and universities work with Mesago closely as advisers, co-organizers and partners. Mesago comprises three companies: Mesago Messe Frankfurt GmbH, Mesago Messemanagement GmbH and Mesago PCIM GmbH.
(mesago.com)